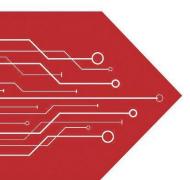
# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Product data sheet

www.msksemi.com







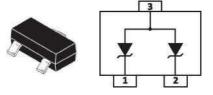
350 Watts peak pulse power per Line(tp=8/20^S) Protects one bidirectional line or two unidirectional lines Low clamping voltage RoHS Compliant

#### **APPLICATIONS**

Cellular Handsets and Accessories Portable Electronics Industrial Controls Set-Top Box Instrumentation Servers, Notebook, and Desktop PC

#### **IECCOMPATIBILITY**

IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC61000-4-4 (EFT) 40A (5/50ns)



SOT-23

#### MAXIMUM RATINGS @25°C UNLESS OTHERWISE SPECIFIED

MAXIMUM RAT INGS @25°c UNLESS OTHERWISE SPECIFIED					
PARAMETER	SY M B OL	VALUE	UNIT		
Peak Pulse Power (tp=8/20 ps waveform)	РРР	350	Watts		
Operadng Temperature Range	TJ	-55-125	°C		
Storage Temperature Range	Tstg	-55-150	°C		

# ELECTRICAL CHARACTERISTICS PER LINE@ 25°C UNLESS OTHERWISE SPECIFIED

	ELECTRICAL	CHARACTER	RISTICS PER	LINE @ 25°c	UNLESS OTH	ERWISE SPEC	IFIED		
PART NUMBER	MARKING	V RWM (V) Max.	V BR (V) Min.	IT (mA)	V c @1A Max.	V Max.	c @A	1 R (uA) Max.	Ст (рF) Мах
MSKSM03	M03	3.3	4.0	1	6.5	15.0	25	100	400
MSKSM05	M05	5.0	6.0	1	9.8	16.0	24	10	300
MSKSM08	M08	8.0	8.5	1	13.4	19.0	18	5	250
MSKSM12	M12	12.0	13.3	1	19.0	24.0	13	1	150
MSKSM15	M15	15.0	16.7	1	24.0	28.0	6	1	100
MSKSM24	M24	24.0	26.7	1	43.0	52.0	6	1	90





#### **Electrical Parameter**

Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
V <sub>RWM</sub>	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
I <sub>T</sub>	Test Current
$V_{BR}$	Breakdown Voltage @ I⊤

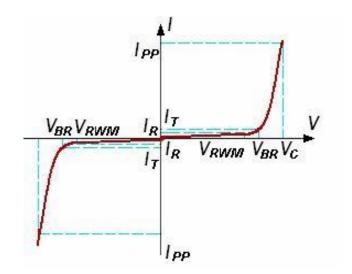


FIG1: Pulse Waveform

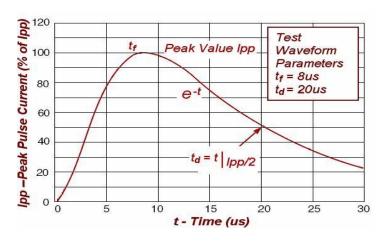
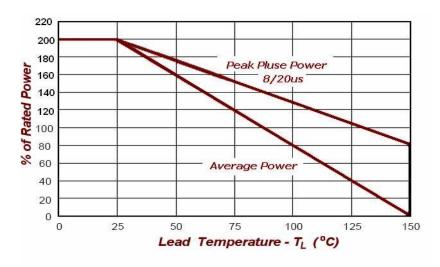
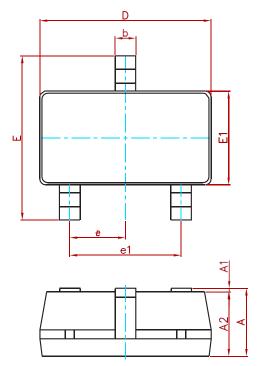


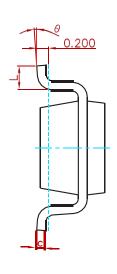
FIG2:Power Derating





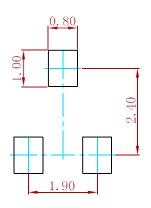
#### **PACKAGE MECHANICAL DATA**





Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Syllibol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
Е	2.650	2.950	0.104	0.116	
е	0.950(	BSC)	0.037	(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
0	0°	8°	0°	8°	

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
MSKSM03-MSKSM24	SOT-23	3000

Semiconductor



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